Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a leadless medium power DFN2020MD-6 (SOT1220) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- · Logic-level compatible
- Extended temperature range T_i = 175 °C
- Side wettable flanks for optical solder inspection
- Small and leadless ultra thin SMD plastic package: 2 x 2 x 0.65 mm
- Trench MOSFET technology
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- · High-side load switch
- · Switching circuits

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C	-	-	-60	V
V_{GS}	gate-source voltage		-20	-	20	V
I _D	drain current	V _{GS} = -10 V; T _{sp} = 25 °C	-	-	-8	Α
P _{tot}	total power dissipation	T _{sp} = 25 °C	-	-	15	W
Static chara	acteristics					
R _{DSon}	drain-source on-state resistance	V_{GS} = -10 V; I_D = -3 A; T_j = 25 °C	-	95	120	mΩ



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain		
2	D	drain	1 1 1 1 6	D
3	G	gate		
4	S	source	2 5	$_{G}$
5	D	drain	3 8 4	
6	D	drain	Transparent top view	S
7	D	drain	DFN2020MD-6 (SOT1220)	017aaa094
8	S	source		

6. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
BUK9D120-60P		plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1220		

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9D120-60P	RJ

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-60	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = -10 V; T _{sp} = 25 °C		-	-8	Α
		V _{GS} = -10 V; T _{sp} = 100 °C		-	-5.1	Α
		V _{GS} = -10 V; T _{amb} = 25 °C	[1]	-	-3	Α
I _{DM}	peak drain current	T_{sp} = 25 °C; single pulse; $t_p \le 10 \mu s$		-	-32	Α
P _{tot}	total power dissipation	T _{sp} = 25 °C		-	15	W
		T _{amb} = 25 °C	[1]	-	2.3	W
Tj	junction temperature			-55	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C
Source-drain	n diode					
Is	source current	T _{sp} = 25 °C		-	-8	Α
		T _{amb} = 25 °C	[1]	-	-2.3	Α
I _{SM}	peak source current	single pulse; $t_p \le 10 \mu s$; $T_{sp} = 25 °C$		-	-32	Α
Avalanche r	uggedness					,
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	$T_{j(init)}$ = 25 °C; I_D = -1.6 A; DUT in avalanche (unclamped)		-	28	mJ

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

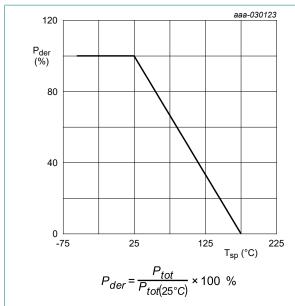


Fig. 1. Normalized total power dissipation as a function of solder point temperature

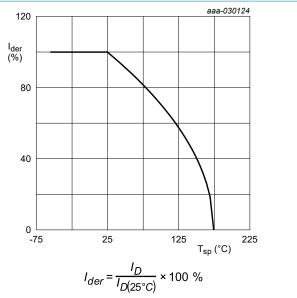


Fig. 2. Normalized continuous drain current as a function of solder point temperature

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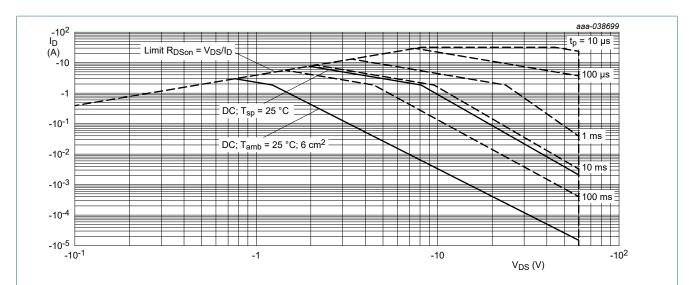


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	57	66	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point			-	6	10	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

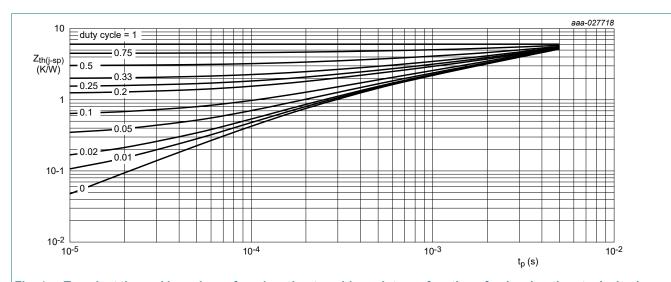


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration; typical values

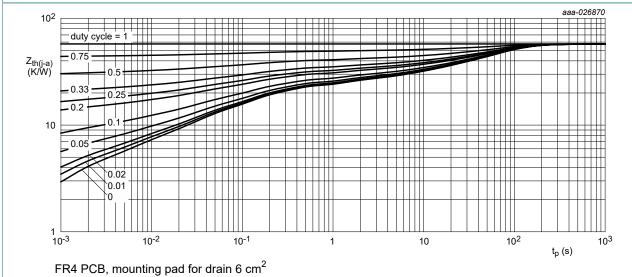


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
V _{(BR)DSS}	drain-source breakdown voltage	$I_D = -250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = 25 \ ^{\circ}C$	-60	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu A; V_{DS} = V_{GS}; T_j = 25 °C$	-1.5	-2	-2.5	V
I _{DSS}	drain leakage current	V _{DS} = -60 V; V _{GS} = 0 V; T _j = 25 °C	-	-	-1	μΑ
		V _{DS} = -60 V; V _{GS} = 0 V; T _j = 125 °C	-	-	-20	μΑ
I _{GSS}	gate leakage current	$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-	-100	nA
		V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-	-	100	nA
R _{DSon}	drain-source on-state	V_{GS} = -10 V; I_D = -3 A; T_j = 25 °C	-	95	120	mΩ
resis	resistance	V _{GS} = -10 V; I _D = -3 A; T _j = 175 °C	-	202	256	mΩ
		V _{GS} = -4.5 V; I _D = -2.5 A; T _j = 25 °C	-	112	160	mΩ
9 _{fs}	forward transconductance	V_{DS} = -10 V; I_{D} = -3 A; T_{j} = 25 °C	-	13	-	S
R_G	gate resistance	f = 1 MHz	-	8	-	Ω
Dynamic ch	naracteristics				- 1	
Q _{G(tot)}	total gate charge	V _{DS} = -30 V; I _D = -3 A; V _{GS} = -10 V;	-	12	18	nC
Q _{GS}	gate-source charge	T _j = 25 °C	-	2.1	-	nC
Q_{GD}	gate-drain charge		-	2.4	-	nC
C _{iss}	input capacitance	V _{DS} = -30 V; f = 1 MHz; V _{GS} = 0 V;	-	713	-	pF
C _{oss}	output capacitance	T _j = 25 °C	-	48	-	pF
C _{rss}	reverse transfer capacitance		-	27	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = -30 \text{ V}; I_D = -3 \text{ A}; V_{GS} = -10 \text{ V};$	-	3	-	ns
t _r	rise time	$R_{G(ext)} = 6 \Omega; T_j = 25 °C$	-	4	-	ns
t _{d(off)}	turn-off delay time		-	24	-	ns
t _f	fall time		-	21	-	ns
Source-drai	in diode		'			
V_{SD}	source-drain voltage	I_S = -2.3 A; V_{GS} = 0 V; T_j = 25 °C	-	-0.9	-1.2	V
t _{rr}	reverse recovery time	$I_S = -2.3 \text{ A}$; $dI_S/dt = 100 \text{ A/µs}$;	-	19	-	ns
Q _r	recovered charge	$V_{GS} = 0 \text{ V}; V_{DS} = -30 \text{ V}; T_j = 25 \text{ °C}$	-	15	-	nC

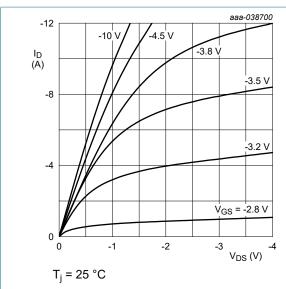


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

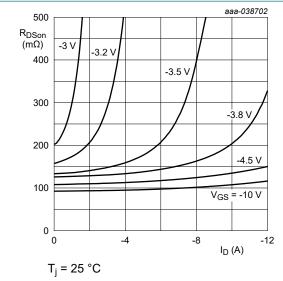
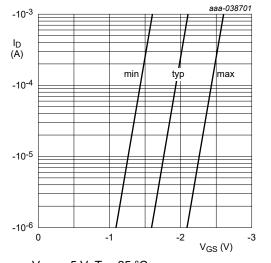


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values



 $V_{DS} = -5 \text{ V}; T_j = 25 \text{ }^{\circ}\text{C}$

Fig. 7. Sub-threshold drain current as a function of gate-source voltage

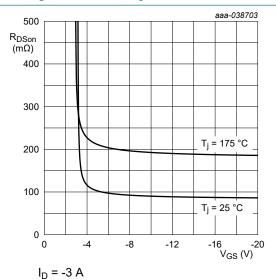


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

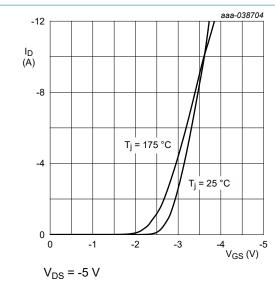


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

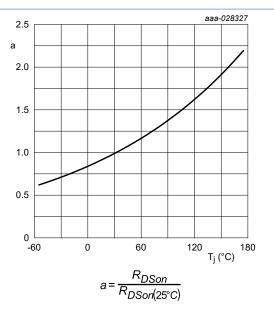


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

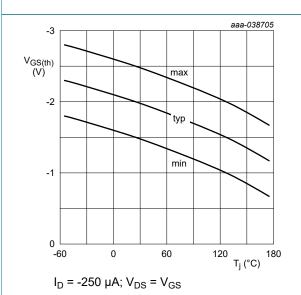
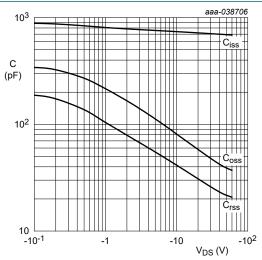


Fig. 12. Gate-source threshold voltage as a function of junction temperature



 $f = 1 MHz; V_{GS} = 0 V$

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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60 V, P-channel Trench MOSFET

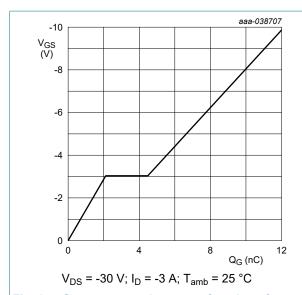


Fig. 14. Gate-source voltage as a function of gate charge; typical values

 $V_{GS} = 0 V$

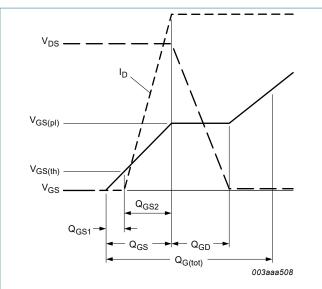


Fig. 15. Gate charge waveform definitions

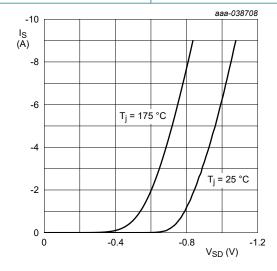
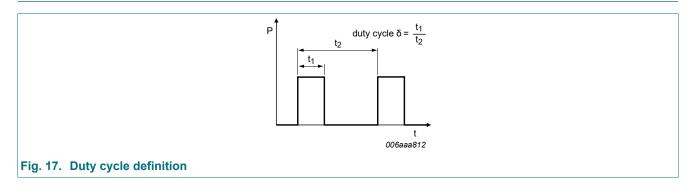


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information



Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

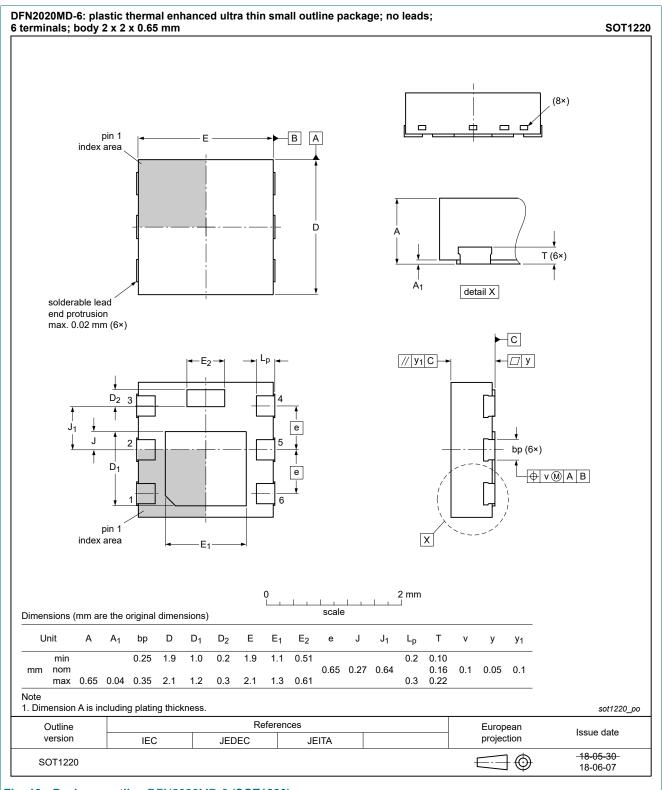
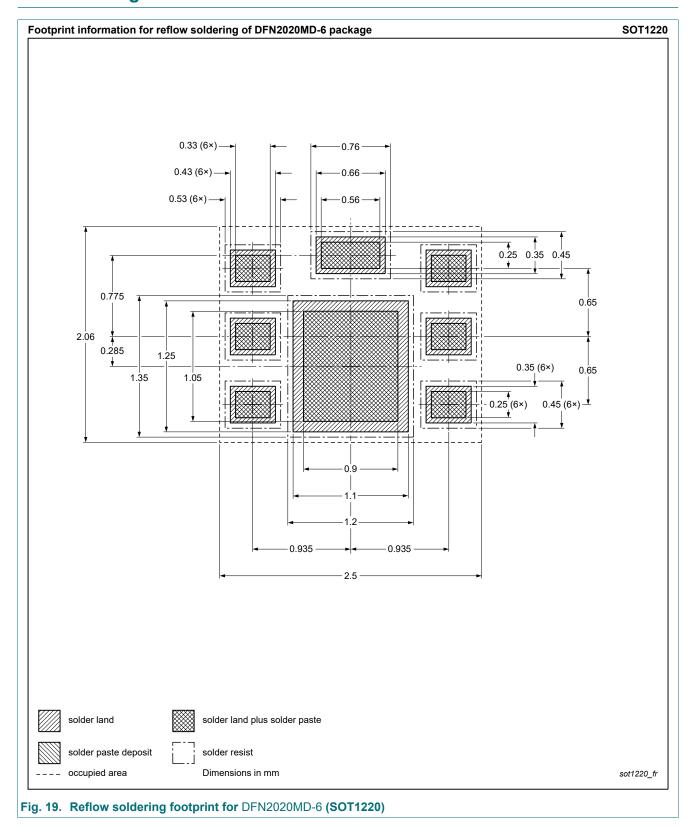


Fig. 18. Package outline DFN2020MD-6 (SOT1220)

13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK9D120-60P v.1	20240209	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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